



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Won Sun Shin, DoSung Chun, SangHo Lee, SeonGoo Lee, Vincent DiCaprio  
Assignee: Amkor Technology, Inc.  
Title: Semiconductor Package And Method For Fabricating The Same  
Serial No.: 09/574,541 Filing Date: May 19, 2000  
Examiner: C. Luu Group Art Unit: 2825  
Batch No.: M03 Date Allowed: 9/17/01  
Docket No.: AB-975 US

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4-4-02

San Jose, California  
December 3, 2001

BOX ISSUE FEE  
COMMISSIONER FOR PATENTS  
Washington, D. C. 20231

**AMENDMENT AFTER ALLOWANCE  
PURSUANT TO 37 C.F.R. §1.312**

Dear Sir:

Pursuant to 37 C.F.R. § 1.312 and co-incident with the payment of the issue fee,  
Applicants respectfully request the entrance of an amendment to the specification.

**IN THE SPECIFICATION**

Please replace the paragraph beginning at page 25, line 6 with the following rewritten paragraph. Attached hereto is a marked-up version of the changes made to the specification by the current amendment. The attached page is captioned "Version with markings to show changes made."

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Other embodiments of semiconductor packages and methods of making them are disclosed in U.S. Patent Application Serial Number 09/566,069, which was filed with the U.S. Patent and Trademark Office on May 5, 2000, and in U.S. Patent Application Serial Number

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